Applications
- CMOS image sensors
- Display devices
- Semiconductor processing for MEMS
- IR cut filters
- Pressure sensors
- Gyroscopes/Accelerometers
- Spectroscopy

Benefits
- CTE match to silicon
- Custom sizes enable higher output/glass utilization
- Flat and smooth surface is excellent for IR/AR coatings and semiconductor processing
- Best in class thickness tolerance eliminates post draw surface grinding and polish process
- Display and semiconductor grade cleanliness
- World-class QA systems and traceability

Capabilities
- Available sizes: 150/200/300mm wafers
- Wafer thickness: 1.1mm – 0.1mm
- Panel availability: up to 500mm x 500mm; custom sizes available upon request
- Panel thickness: 1.1mm – 0.1mm
- Photo lithography and patterning process
- Cavity wafers
- Custom AR and chrome coatings
- Glass to metal seal
- Electroplating
- Complete metrology solutions

Contact us
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